



## APT1608QBC/D

1.6 x 0.8 mm SMD Chip LED Lamp

### DESCRIPTIONS

- The Blue source color devices are made with InGaN Light Emitting Diode
- Electrostatic discharge and power surge could damage the LEDs
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs
- All devices, equipments and machineries must be electrically grounded

### FEATURES

- 1.6 mm x 0.8 mm SMD LED, 0.75 mm thickness
- Low power consumption
- Wide viewing angle
- Ideal for backlight and indicator
- Package: 2000pcs / reel
- Moisture sensitivity level : 3
- RoHS compliant

### APPLICATIONS

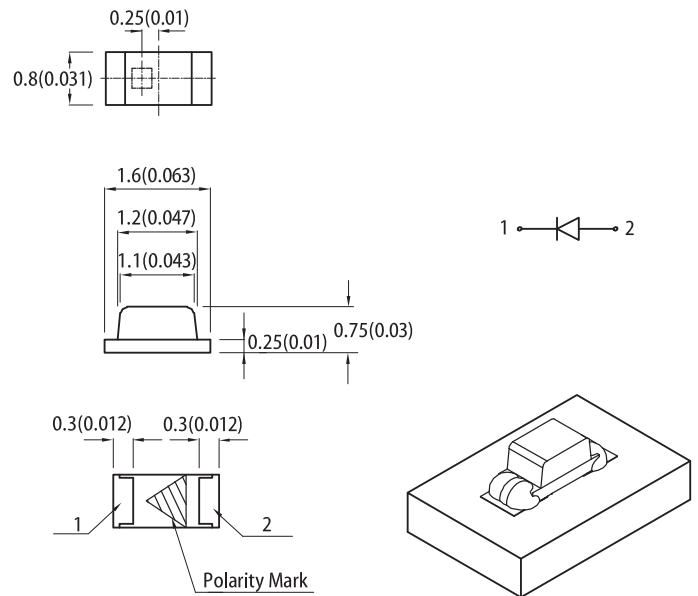
- Backlight
- Status indicator
- Home and smart appliances
- Wearable and portable devices
- Healthcare applications

### ATTENTION

Observe precautions for handling electrostatic discharge sensitive devices

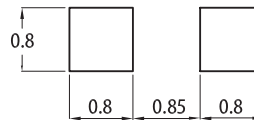


### PACKAGE DIMENSIONS



### RECOMMENDED SOLDERING PATTERN

(units : mm; tolerance : ± 0.1)



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

### SELECTION GUIDE

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA <sup>[2]</sup>		Viewing Angle <sup>[1]</sup>
			Min.	Typ.	2θ1/2
APT1608QBC/D	■ Blue (InGaN)	Water Clear	40	100	130°

- Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
  2. Luminous intensity / luminous flux: +/-15%.
  3. Luminous intensity value is traceable to CIE127-2007 standards.

**ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C**

Parameter	Symbol	Emitting Color	Value		Unit
			Typ.	Max.	
Wavelength at Peak Emission I <sub>F</sub> = 20mA	λ <sub>peak</sub>	Blue	460	-	nm
Dominant Wavelength I <sub>F</sub> = 20mA	λ <sub>dom</sub> <sup>[1]</sup>	Blue	465	-	nm
Spectral Bandwidth at 50% Φ REL MAX I <sub>F</sub> = 20mA	Δλ	Blue	25	-	nm
Capacitance	C	Blue	100	-	pF
Forward Voltage I <sub>F</sub> = 20mA	V <sub>F</sub> <sup>[2]</sup>	Blue	3.3	4	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Blue	-	50	uA
Temperature Coefficient of λ <sub>peak</sub> I <sub>F</sub> = 20mA, -10°C ≤ T ≤ 85°C	TC <sub>λpeak</sub>	Blue	0.04	-	nm/°C
Temperature Coefficient of λ <sub>dom</sub> I <sub>F</sub> = 20mA, -10°C ≤ T ≤ 85°C	TC <sub>λdom</sub>	Blue	0.03	-	nm/°C
Temperature Coefficient of V <sub>F</sub> I <sub>F</sub> = 20mA, -10°C ≤ T ≤ 85°C	TC <sub>V</sub>	Blue	-2.9	-	mV/°C

**Notes:**

1. The dominant wavelength (λ<sub>d</sub>) above is the setup value of the sorting machine. (Tolerance λ<sub>d</sub> : ±1nm.)
2. Forward voltage: ±0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

**ABSOLUTE MAXIMUM RATINGS at T<sub>A</sub>=25°C**

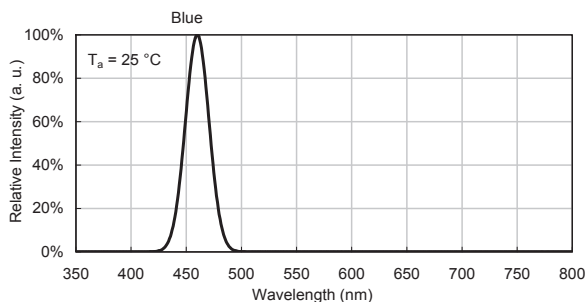
Parameter	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	120	mW
Reverse Voltage	V <sub>R</sub>	5	V
Junction Temperature	T <sub>j</sub>	115	°C
Operating Temperature	T <sub>op</sub>	-40 to +85	°C
Storage Temperature	T <sub>stg</sub>	-40 to +85	°C
DC Forward Current	I <sub>F</sub>	30	mA
Peak Forward Current	I <sub>FM</sub> <sup>[1]</sup>	150	mA
Electrostatic Discharge Threshold (HBM)	-	250	V
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> <sup>[2]</sup>	545	°C/W
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> <sup>[2]</sup>	510	°C/W

**Notes:**

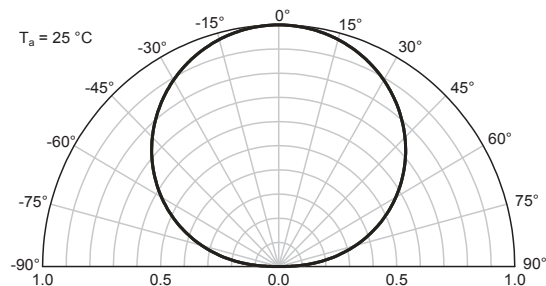
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. R<sub>th JA</sub>, R<sub>th JS</sub> Results from mounting on PC board FR4 (pad size ≥ 16 mm<sup>2</sup> per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

### TECHNICAL DATA

#### RELATIVE INTENSITY vs. WAVELENGTH

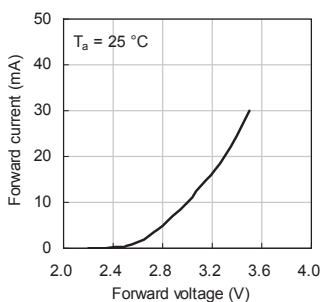


#### SPATIAL DISTRIBUTION

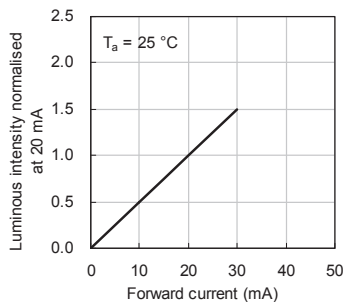


### BLUE

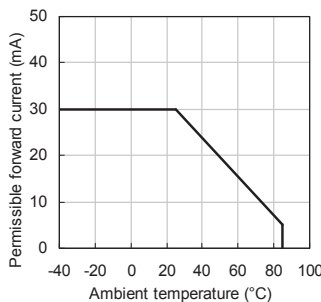
Forward Current vs. Forward Voltage



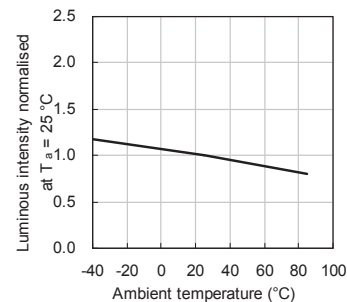
Luminous Intensity vs. Forward Current



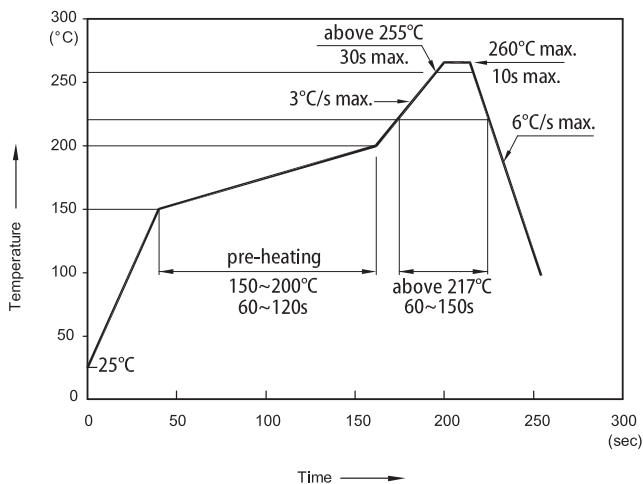
Forward Current Derating Curve



Luminous Intensity vs. Ambient Temperature

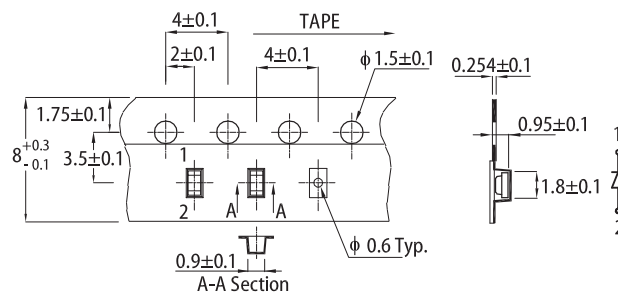


#### REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS



- Notes:
1. Don't cause stress to the LEDs while it is exposed to high temperature.
  2. The maximum number of reflow soldering passes is 2 times.
  3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product.

#### TAPE SPECIFICATIONS (units : mm)



#### REEL DIMENSION (units : mm)

